

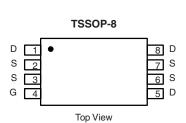
P-Channel 20-V (G-S) MOSFET

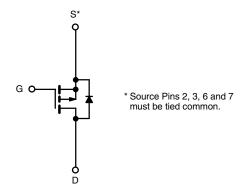
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)		
	0.012 at V _{GS} = - 4.5 V	- 9.0		
-20	0.015 at V _{GS} = - 2.5 V	- 7.8		
	0.020 at V _{GS} = - 1.8 V	- 6.0		

FEATURES

- Halogen-free
- TrenchFET® Power MOSFETs







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	$I_A = 25$ °C, unles	s otnerwise n	otea		
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V_{DS}	-20		V
Gate-Source Voltage		V _{GS}	± 12		V
Operation of Decision Community (T. 150,00)	T _A = 25 °C	I _D	- 9.0	-7.8	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		- 6.8	-5.8	
Pulsed Drain Current (10 μs Pulse Width)		I _{DM}	- 30		Α
Continuous Source Current (Diode Conduction) ^a		I _S	- 1.35	- 0.95	
Maniana Bana Biratantan	T _A = 25 °C	P _D	1.5	1.05	W
Maximum Power Dissipation ^a	T _A = 70 °C		1.0	0.67	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Marrian una lumation ta Ambianti	t ≤ 10 s	R_{thJA}	65	83	
Maximum Junction-to-Ambient ^a	Steady State	¹¹thJA	100	120	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	43	52	

Notes: a. Surface Mounted on 1" x 1" FR4 board.

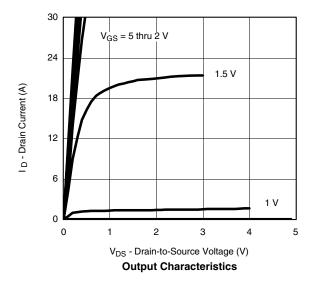


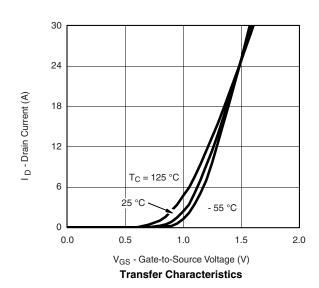
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -450 \mu A$	- 0.45	-	1.0	٧	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	,	V _{DS} = - 20 V, V _{GS} = 0 V			- 1	μΑ	
	I _{DSS}	V_{DS} = -20V, V $_{GS}$ = 0 V, T_{J} = 70 °C			- 25		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 4.5 V	- 20			Α	
		V _{GS} = - 4.5 V, I _D = - 8.0 A		0.010			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 7.0 A		0.012		Ω	
		V _{GS} = - 1.8 V, I _D = - 5.8 A		0.016			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 5 V, I _D = - 8.0 A		44		S	
Diode Forward Voltage ^a	V_{SD}	I _S = - 1.5 A, V _{GS} = 0 V		- 0.56	- 1.1	V	
Dynamic ^b				•			
Total Gate Charge	Q_g			46	70	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -8.0 \text{ A}$		5			
Gate-Drain Charge	Q_{gd}			15.5			
Turn-On Delay Time	t _{d(on)}			45	70		
Rise Time	t _r	V_{DD} = - 10 V, R = 6 Ω		85	130		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 6 Ω		220	400	ns	
Fall Time	t _f			155	235		
Source-Drain Reverse Recovery Time	t _{rr}	I _F = - 1.5 A, di/dt = 100 A/μs		140	210		

- Notes: a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

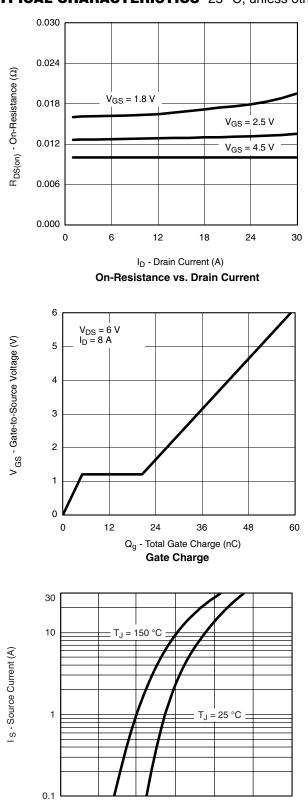
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted







TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



0.0

0.2

0.4

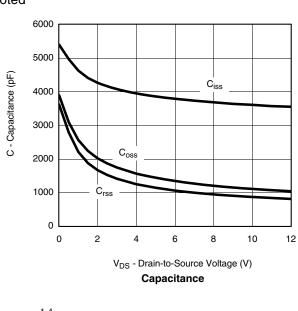
0.6

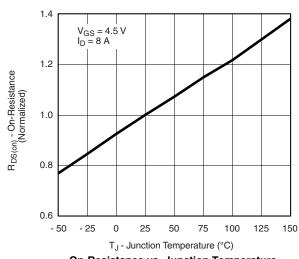
 V_{SD} - Source-to-Drain Voltage (V) **Source-Drain Diode Forward Voltage**

0.8

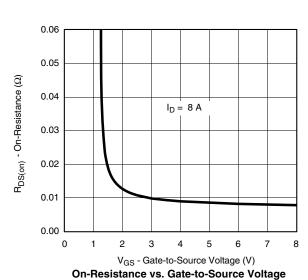
1.0

1.2



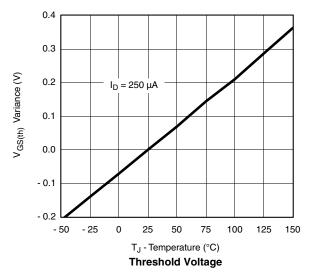


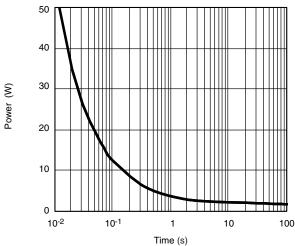
On-Resistance vs. Junction Temperature

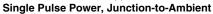


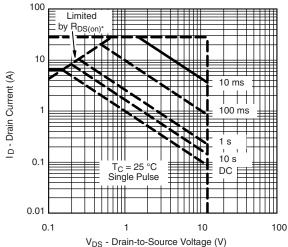


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



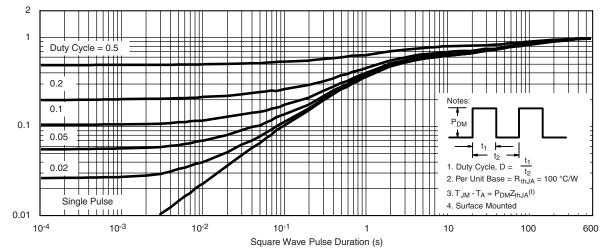






* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Case

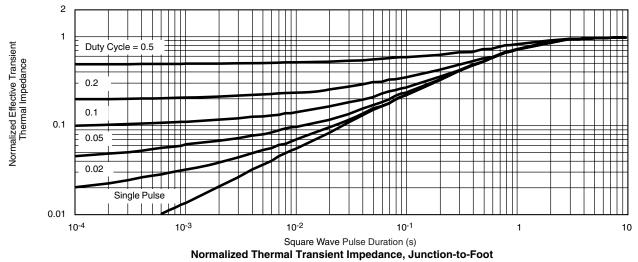


Normalized Thermal Transient Impedance, Junction-to-Ambient

Normalized Effective Transient Thermal Impedance



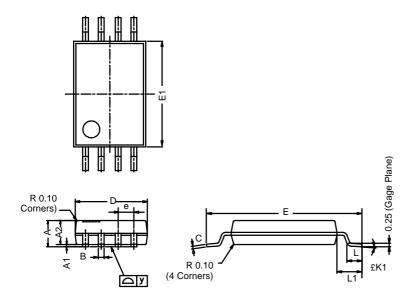
TYPICAL CHARACTERISTICS $\,25\,^{\circ}\text{C}$, unless otherwise noted





TSSOP: 8-LEAD

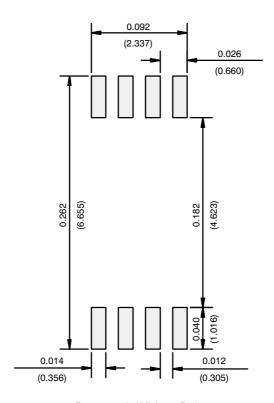
JEDEC Part Number: MO-153



	MILLIMETERS					
Dim	Min	Nom	Max			
Α	-	-	1.20			
A ₁	0.05	0.10	0.15			
A ₂	0.80	1.00	1.05			
В	0.19	0.28	0.30			
С	-	0.127	-			
D	2.90	3.00	3.10			
E	6.20	6.40	6.60			
E ₁	4.30	4.40	4.50			
е	-	0.65	-			
L	0.45	0.60	0.75			
L ₁	0.90	1.00	1.10			
Υ	-	-	0.10			
£K1	0°	3°	6°			
ECN: S-03946—Rev. G, 09-Jul-01 DWG: 5844						



RECOMMENDED MINIMUM PADS FOR TSSOP-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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